THE DATASHEET OF

IRG4BC30FD-S

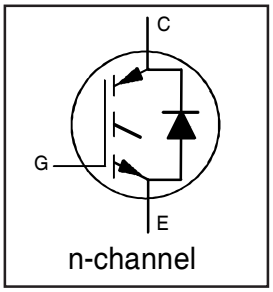
PD - 95970A

International
IOR Rectifier

IRG4BC30FD-SPbF

Fast CoPack IGBT

INSULATED GATE BIPOLAR TRANSISTOR WITH HYPERFAST DIODE



n-channel

V_{CES} = 600V

$V_{CE(on)\ typ.}$ = 1.59V

@V_{GE} = 15V, I_C = 17A

D²Pak

Features

- Fast: optimized for medium operating frequencies (1-5 kHz in hard switching, >20kHz in resonant mode).
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than Generation 3.
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft recovery anti-parallel diodes for use in bridge configurations.
- Lead-Free

Benefits

- Generation 4 IGBT's offer highest efficiency available.
- IGBT's optimized for specific application conditions.
- HEXFRED diodes optimized for performance with IGBT's. Minimized recovery characteristics require less/no snubbing.
- Designed to be a "drop-in" replacement for equivalent industry-standard Generation 3 IR IGBT's.

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
I_C @ T_C = 25°C	Continuous Collector Current	31	A
I_C @ T_C = 100°C	Continuous Collector Current	17	
I_{CM}	Pulse Collector Current (Ref.Fig.C.T.5) ①	124	
I_{LM}	Clamped Inductive Load current ②	124	
I_F @ T_C = 100°C	Diode Continuous Forward Current	12	
I_{FM}	Diode Maximum Forward Current	120	
V_{GE}	Gate-to-Emitter Voltage	±20	V
P_D @ T_C = 25°C	Maximum Power Dissipation	100	W
P_D @ T_C = 100°C	Maximum Power Dissipation	42	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

Thermal / Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case- IGBT	—	—	1.2	°C/W
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mounted,steady state)⑤	—	—	40	
Wt	Weight	—	2.0 (0.07)	—	g (oz.)

01/27/10

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage ③	600	—	—	V	V_{GE} = 0V, I_C = 250µA
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.69	—	V/°C	V_{GE} = 0V, I_C = 1mA
$V_{CE(on)}$	Collector-to-Emitter Voltage	—	1.59	1.8	V	I_C = 17A V_{GE} = 15V
		—	1.99	—		I_C = 31A See Fig. 2, 5
		—	1.7	—		I_C = 17A, T_J = 150°C
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0	V	V_{CE} = V_{GE}, I_C = 250µA
$\Delta V_{GE(th)}/\Delta T_J$	Threshold Voltage temp. coefficient	—	-11	—	mV/°C	V_{CE} = V_{GE}, I_C = 250µA
gfe	Forward Transconductance ④	6.1	10	—	S	V_{CE} = 100V, I_C = 17A
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	µA	V_{GE} = 0V, V_{CE} = 600V
		—	—	2500		V_{GE} = 0V, V_{CE} = 600V, T_J = 150°C
V_{FM}	Diode Forward Voltage Drop	—	1.4	1.7	V	I_F = 12A See Fig. 13
		—	1.3	1.6		I_F = 12A, T_J = 150°C
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
Q_g	Total Gate Charge (turn-on)	—	51	77	nC	I_C = 17A	
Q_{ge}	Gate-to-Emitter Charge (turn-on)	—	7.9	12		V_{CC} = 400V See Fig. 8	
Q_{gc}	Gate-to-Collector Charge (turn-on)	—	19	28		V_{GE} = 15V	
$t_{d(on)}$	Turn-On delay time	—	42	—	ns	T_J = 25°C	
t_r	Rise time	—	26	—		I_C = 17A, V_{CC} = 480V	
$t_{d(off)}$	Turn-Off delay time	—	230	350		V_{GE} = 15V, R_G = 23Ω	
t_f	Fall time	—	160	230		Energy losses inlcude "tail" and	
E_{on}	Turn-On Switching Loss	—	0.63	—	mJ	diode reverse recovery.	
E_{off}	Turn-Off Switching Loss	—	1.39	—		See Fig. 9, 10, 11, 18	
E_{ts}	Total Switching Loss	—	2.02	3.9			
$t_{d(on)}$	Turn-On delay time	—	42	—	ns	T_J = 150°C See Fig. 9,10,11,18	
t_r	Rise time	—	27	—		I_C = 17A, V_{CC} = 480V	
$t_{d(off)}$	Turn-Off delay time	—	310	—		V_{GE} = 15V, R_G = 23Ω	
t_f	Fall time	—	310	—		Energy losses inlcude "tail" and	
E_{ts}	Total Switching Loss	—	3.2	—	mJ	diode reverse recovery.	
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package	
C_{ies}	Input Capacitance	—	1100	—	pF	V_{GE} = 0V	
C_{oes}	Output Capacitance	—	74	—		V_{CC} = 30V See Fig. 7	
C_{res}	Reverse Transfer Capacitance	—	14	—		f = 1.0MHz	
t_{rr}	Diode Reverse Recovery Time	—	42	60	ns	T_J = 25°C See Fig.	
		—	80	120		T_J = 125°C 14	I_F = 12A
I_{rr}	Diode Peak Reverse Recovery Current	—	3.5	6.0	A	T_J = 25°C See Fig.	
		—	5.6	10		T_J = 125°C 15	V_R = 200V
Q_{rr}	Diode Reverse Recovery Charge	—	80	180	nC	T_J = 25°C See Fig.	
			220	600		T_J = 125°C 16	di/dt 200A/µs
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery	—	180	—	A/µs	T_J = 25°C See Fig.	
	During t_b	—	120	—		T_J = 125°C 17	

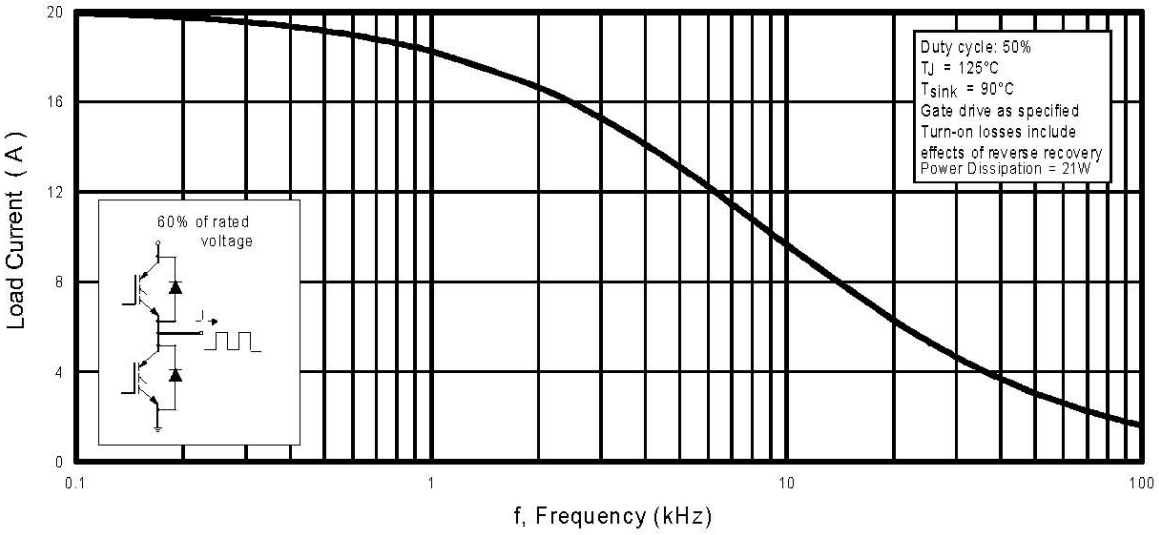


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

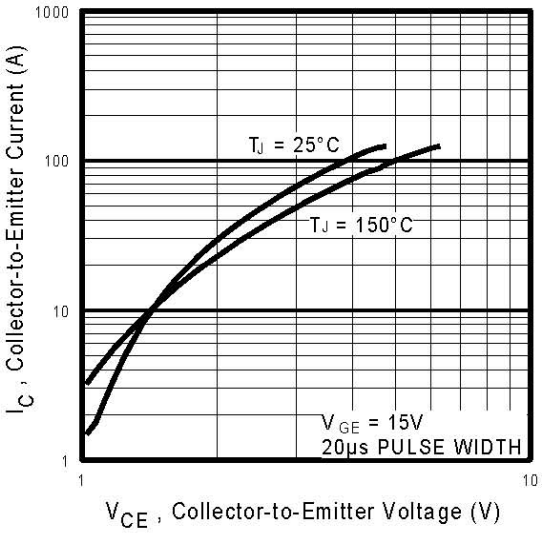


Fig. 2 - Typical Output Characteristics

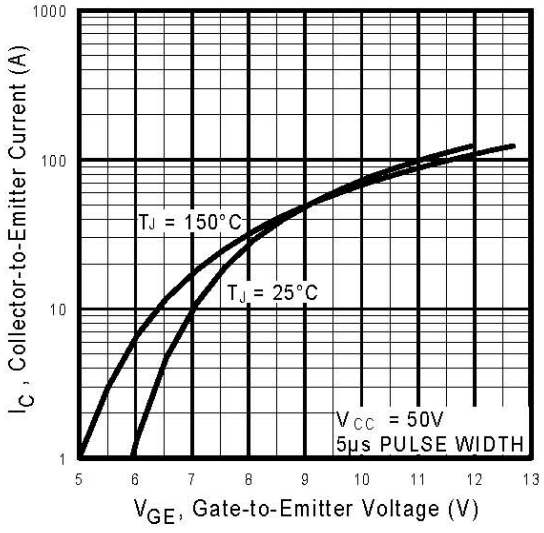


Fig. 3 - Typical Transfer Characteristics

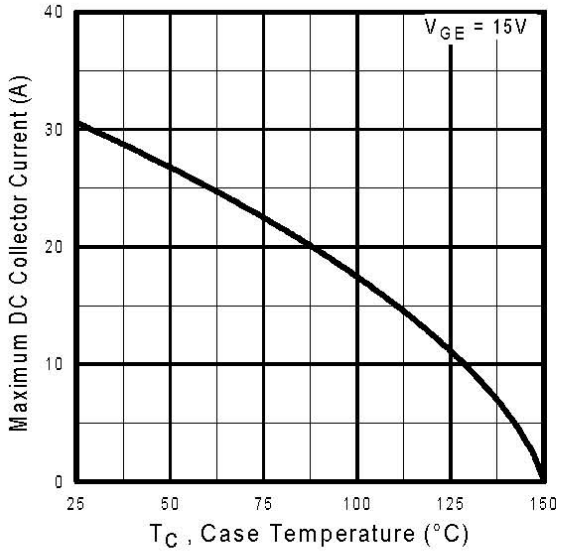


Fig. 4 - Maximum Collector Current vs. Case Temperature

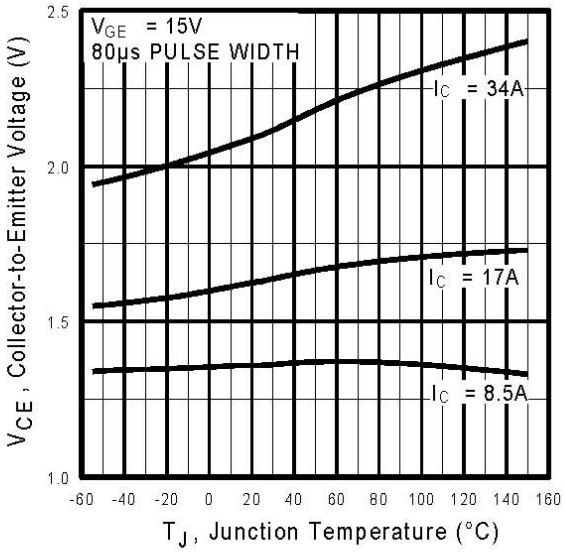


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

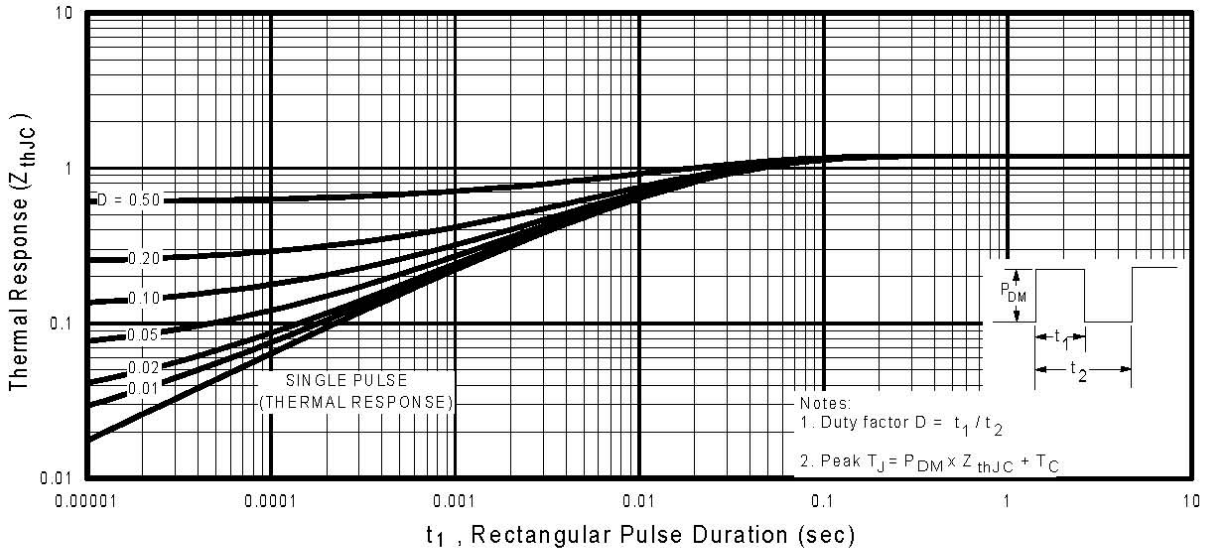


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

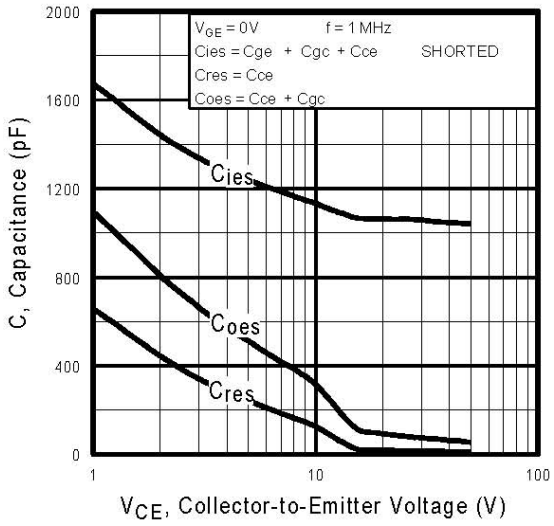


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

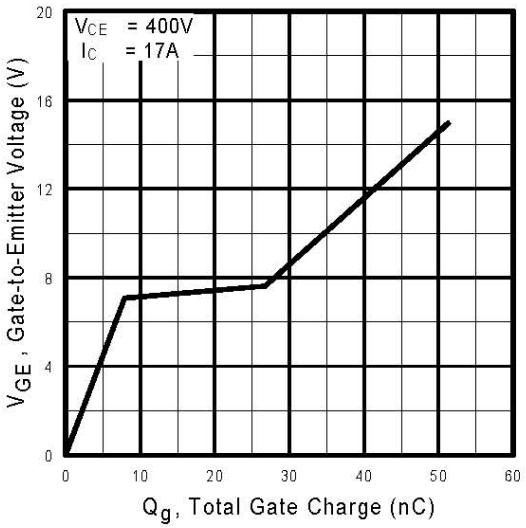


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

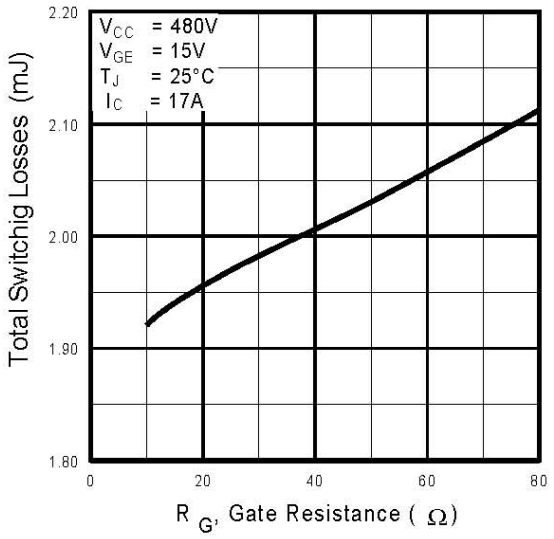


Fig. 9 - Typical Switching Losses vs. Gate Resistance

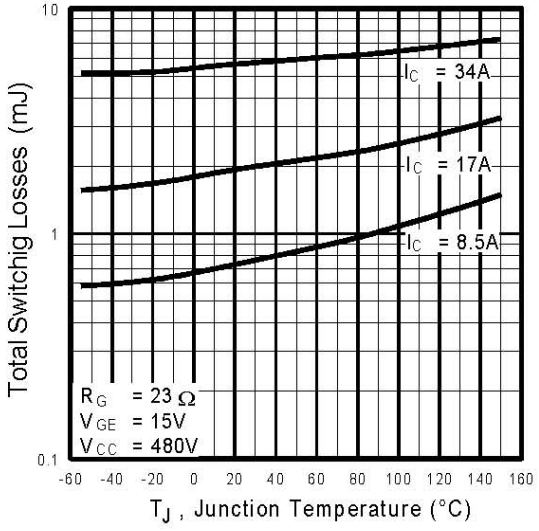


Fig. 10 - Typical Switching Losses vs. Junction Temperature

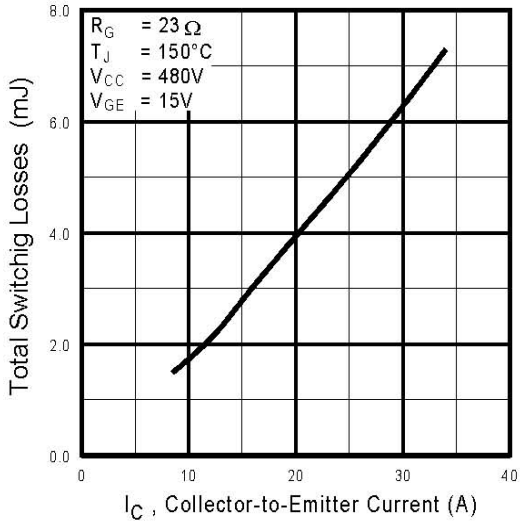


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

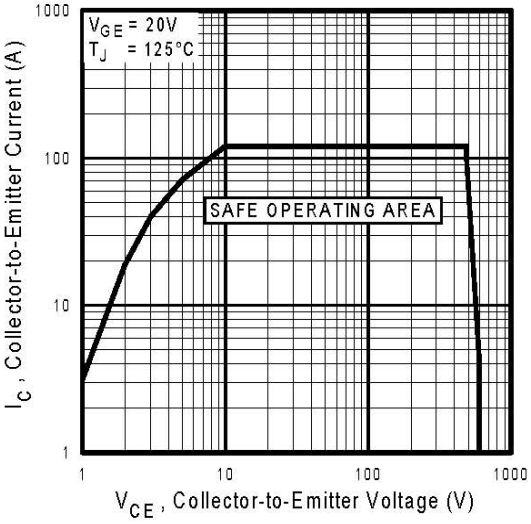


Fig. 12 - Turn-Off SOA

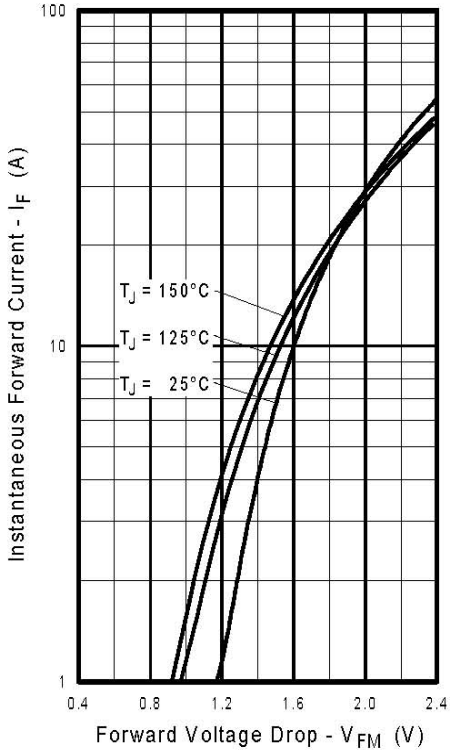


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

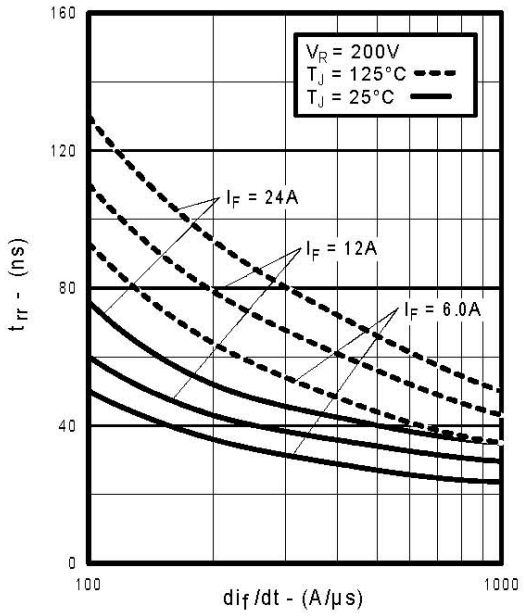


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

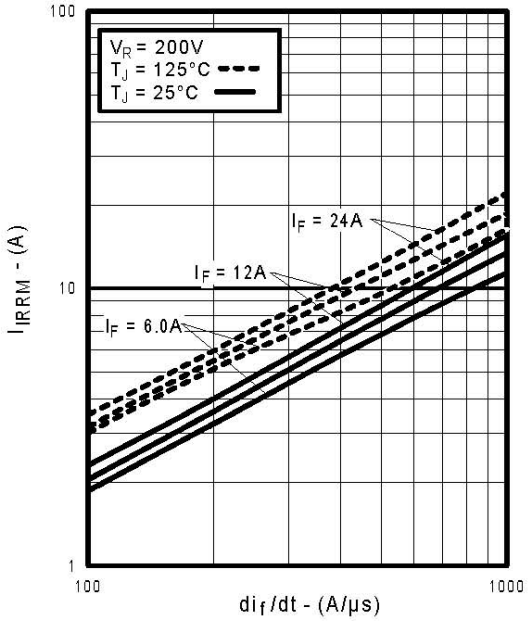


Fig. 15 - Typical Recovery Current vs. di_f/dt

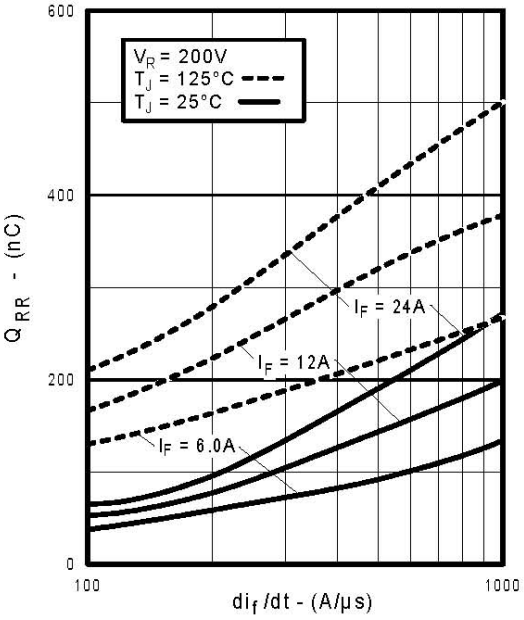


Fig. 16 - Typical Stored Charge vs. di_f/dt

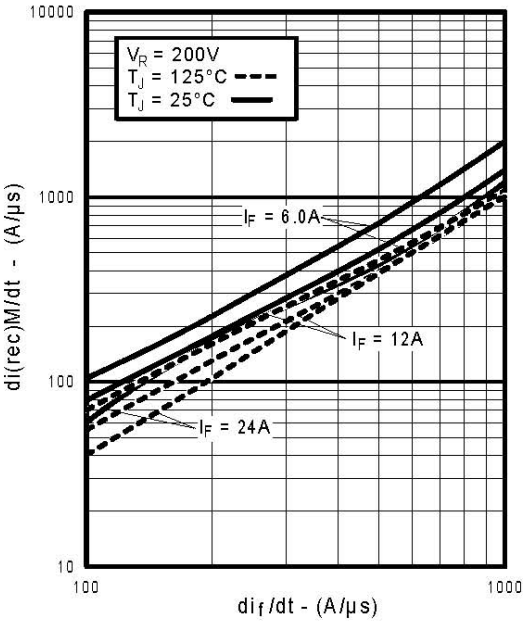


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

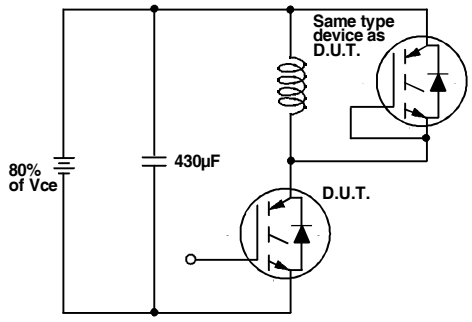


Fig. 18a - Test Circuit for Measurement of I_{LM}, E_{on}, $E_{off(diode)}$, t_{rr}, Q_{rr}, I_{rr}, $t_{d(on)}$, t_r, $t_{d(off)}$, t_f

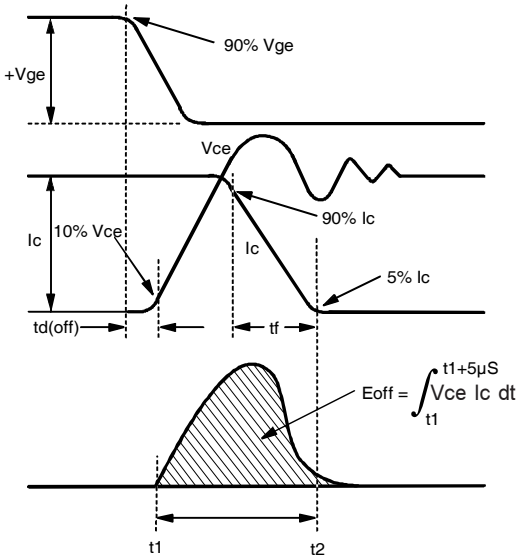


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off}, $t_{d(off)}$, t_f

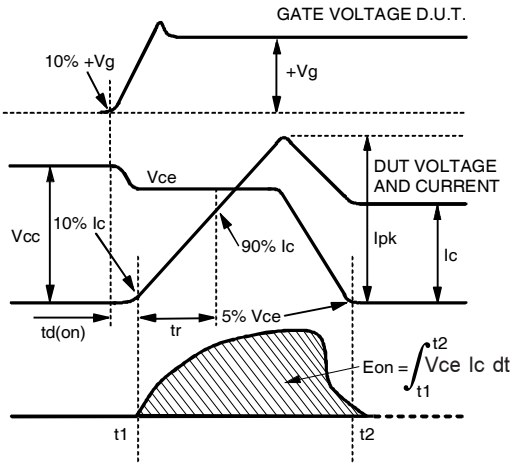


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on}, $t_{d(on)}$, t_r

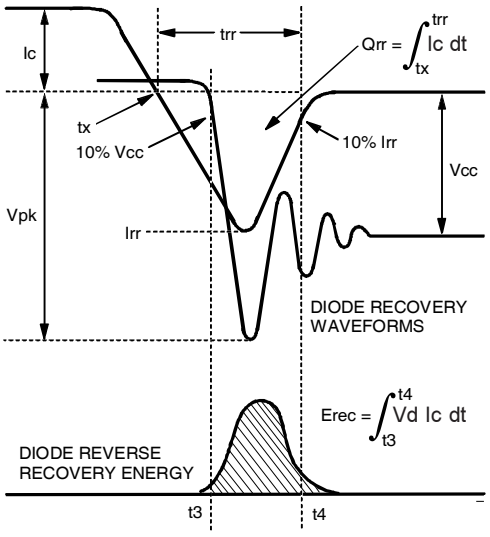


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec}, t_{rr}, Q_{rr}, I_{rr}

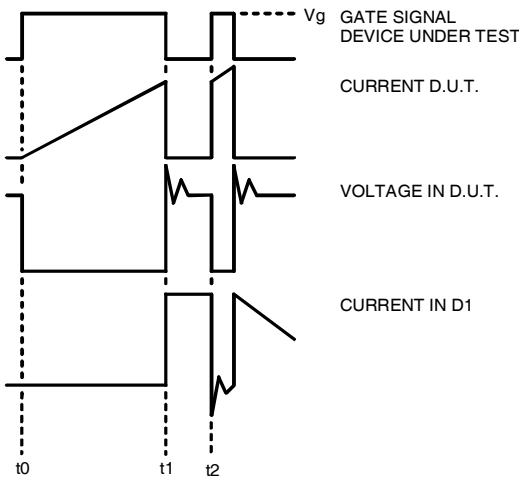


Fig.18e - Macro Waveforms for Figure 18a's Test Circuit

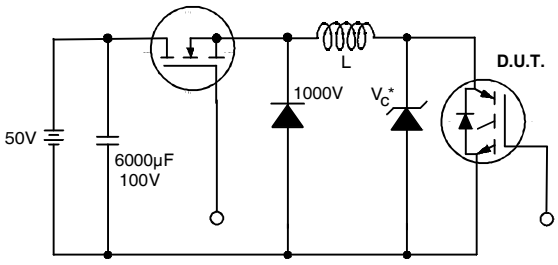
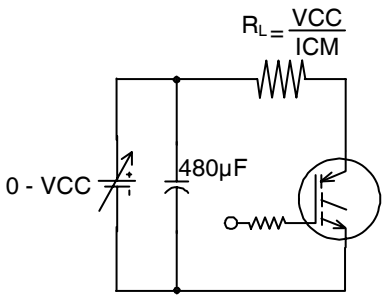


Fig. 19 - Clamped Inductive Load Test Circuit



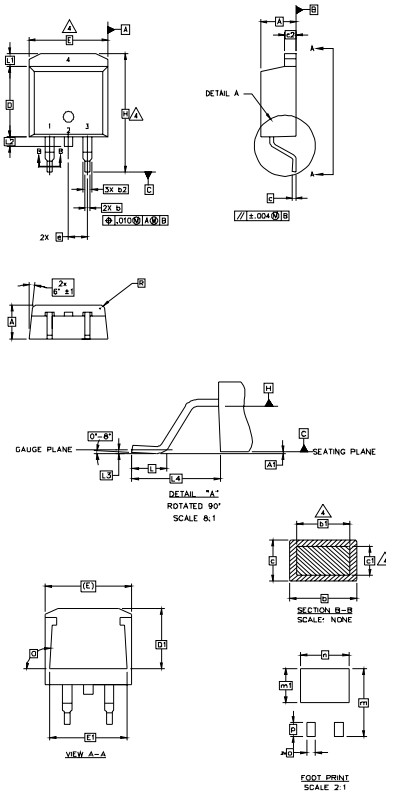
Pulsed Collector Current
Test Circuit

Fig. 20 - Pulsed Collector Current Test Circuit

International
IOR Rectifier

D²Pak Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.78	.045	.070	
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	4
c2	1.14	1.65	.045	.065	
D	8.51	9.65	.335	.380	3
D1	6.86		.270		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1		1.65		.065	
L2	1.27	1.78	.050	.070	
L3	0.25 BSC		.010 BSC		
L4	4.78	5.28	.188	.208	
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
o	2.08		.082		
p	3.81		.150		
R	0.51	0.71	.020	.028	
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

HEXFET

1.- GATE
2, 4.- DRAIN
3.- SOURCE

IGBTs, CoPACK

1.- GATE
2, 4.- COLLECTOR
3.- EMITTER

DIODES

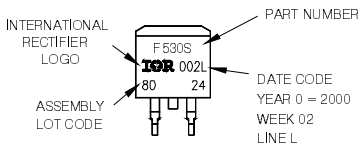
1.- ANODE *
2, 4.- CATHODE
3.- ANODE

* PART DEPENDENT.

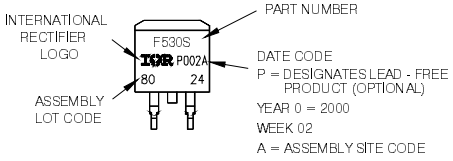
D²Pak Part Marking Information

EXAMPLE: THIS IS AN IRF530S WITH
LOT CODE 8024
ASSEMBLED ON WW 02, 2000
IN THE ASSEMBLY LINE 'L'

Note: "P" in assembly line position indicates "Lead - Free"



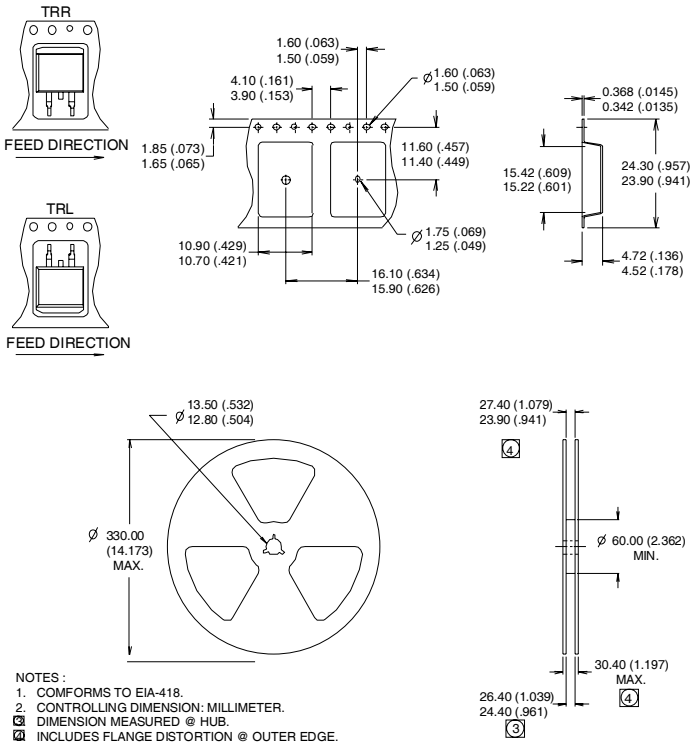
OR



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

D²Pak Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :
1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION MEASURED @ HUB.
4. INCLUDES FLANGE DISTORTION @ OUTER EDGE.

Notes:

① Repetitive rating: V_{GE}=20V; pulse width limited by maximum junction temperature (figure 20).

② V_{CC}=80%(V_{CES}), V_{GE}=20V, L=10µH, R_G = 23Ω (figure 19).

③ Pulse width ≤ 80µs; duty factor ≤ 0.1%.

④ Pulse width 5.0µs, single shot.

⑤ When mounted on 1" square PCB (FR-4 or G-10 Material).

Data and specifications subject to change without notice.

International
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903
Visit us at www.irf.com for sales contact information. 01/2010

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- View IRG4BC30FD-S on WIN SOURCE
- Infineon Technologies Information

Optimize Your Supply Chain with WIN SOURCE Solutions

- Global Sourcing Solution
- Obsolete Management
- Cost Control Management
- Shortage Management
- Alternative Solution
- Excess Inventory Management